



Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy, t=0.20mm
- 1.3 Shell: copper alloy, t=0.25mm

2. Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
- 2.7 Temperature range: -30°C~80°C

RECOMMENDED PCB LAYOUT

A

设计 DRAW BY	杨帆	审核 DISCUSS BY		HDC有限公司	图名 DRAWING NO	MICRO USB B TYPE 外壳DIP 6.4 有柱	图号 SHEET NO	067	日期 DATE	2009.4.15
校对 DISCUSS BY		比例 SCALE	2:1		客户 VERSION		数量 QUAN	备注 REMARK	版次 REMARK	张号 SHEET